#### Nch 650V 24A Power MOSFET

V <sub>DSS</sub>	650V
R <sub>DS(on)</sub> (Max.)	0.185Ω
I <sub>D</sub>	±24A
$P_D$	245W

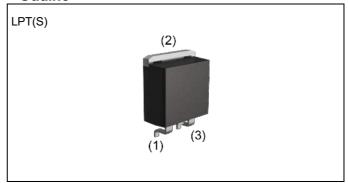
# ●Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

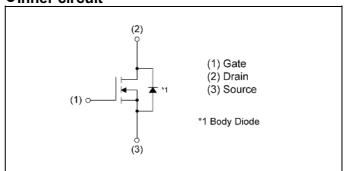
### Application

Switching

#### Outline



#### •Inner circuit



Packaging specifications

Packing	Embossed Tape
Packing code	TL
Marking	R6524ENJ
Basic ordering unit (pcs)	1000

## ullet Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V <sub>DSS</sub>	650	V
Continuous drain current (T <sub>c</sub> = 25°C)		I <sub>D</sub> *1	±24	Α
Pulsed drain current	I <sub>DP</sub> *2	±72	Α	
Cata Carrage walkana	static		±20	V
Gate - Source voltage	AC(f>1Hz)	V <sub>GSS</sub>	±30	V
Avalanche current, single pulse	·	I <sub>AS</sub>	4.1	Α
Avalanche energy, single pulse		E <sub>AS</sub> *3	654	mJ
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	245	W	
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage tempera	ature range	T <sub>stg</sub>	-55 to +150	°C

#### ●Thermal resistance

Downwortow	Cymah al	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *4	-	-	0.51	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *5	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

## ●Electrical characteristics (T<sub>a</sub> = 25°C)

Davameter	Cymaela al	Conditions	Values			Linit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage V <sub>(BR)DSS</sub>		V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	650	-	1	V	
		V <sub>DS</sub> = 650V, V <sub>GS</sub> = 0V					
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	100	μΑ	
		$T_j = 125^{\circ}C$	-	-	1000		
Gate - Source leakage current	$I_{GSS}$	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	-	-	±100	nA	
Gate threshold voltage	$V_{\text{GS(th)}}$	$V_{DS} = V_{GS}, I_{D} = 750 \mu A$	2	-	4	V	
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 11.3A					
Static drain - source on - state resistance	R <sub>DS(on)</sub> *6	$T_j = 25^{\circ}C$	-	0.160	0.185	Ω	
		$T_j = 125^{\circ}C$	-	-	-		
Gate resistance	$R_G$	f = 1MHz, open drain	-	6.5	-	Ω	

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatar	Cymah al	Conditions		Unit		
Parameter	Symbol Conditions Min. Typ		Тур.	Max.	Uniil	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	1650	-	
Output capacitance C <sub>oss</sub>		V <sub>DS</sub> = 25V	-	1850	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	220	1	
Turn - on delay time	t <sub>d(on)</sub> *6	$V_{DD} \simeq 300V$ , $V_{GS} = 10V$	-	30	-	
Rise time $t_r^{*6}$		I <sub>D</sub> = 12A	-	55	-	
Turn - off delay time $t_{d(off)}^{*6}$		$R_L \simeq 27.4\Omega$	-	180	-	ns
Fall time	<b>t</b> <sub>f</sub> *6	$R_G = 10\Omega$	-	55	-	

### ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Daramatar	Cymah al	Conditions	Values			l limit	
Parameter	Symbol	Symbol Conditions		Тур.	Max.	Unit	
Total gate charge	$Q_g^{*6}$	V <sub>DD</sub> ≈ 300V	-	70	-		
Gate - Source charge	Q <sub>gs</sub> *6	I <sub>D</sub> = 24A	-	10	-	nC	
Gate - Drain charge	Q <sub>gd</sub> *6	V <sub>GS</sub> = 10V	-	35	-		
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 300V, I <sub>D</sub> = 24A	-	5.8	-	V	

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L $\doteqdot$ 70mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>i</sub>=25 $^{\circ}$ C

<sup>\*4</sup> T<sub>C</sub>=25°C

<sup>\*5</sup> Mounted on an epoxy PCB FR4 (25mm x 27mm x 0.8mm)

<sup>\*6</sup> Pulsed

## ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions		Unit			
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Source current	I <sub>S</sub> *1	T <sub>C</sub> = 25°C	1	-	24	Α	
Pulsed source current	l <sub>SP</sub> *2	1C - 23 C	1	-	72	Α	
Source-Drain voltage	V <sub>SD</sub> *6	$V_{GS} = 0V, I_{S} = 24A$	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *6		-	540	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *6	I <sub>S</sub> = 24A di/dt = 100A/µs	-	9.5	-	μC	
Peak reverse recovery current	I <sub>rr</sub> *6		-	35	-	Α	

Fig.1 Power Dissipation Derating Curve

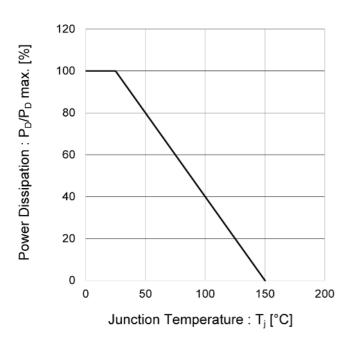


Fig.2 Drain Current Derating Curve

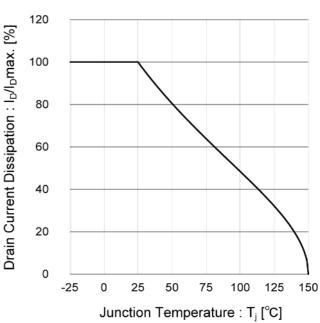


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

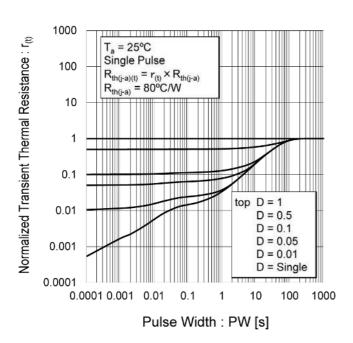


Fig.4 Maximum Safe Operating Area

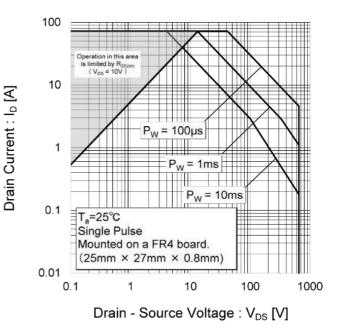


Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

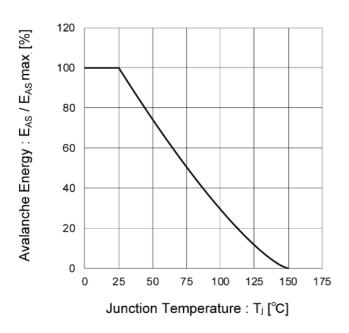


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

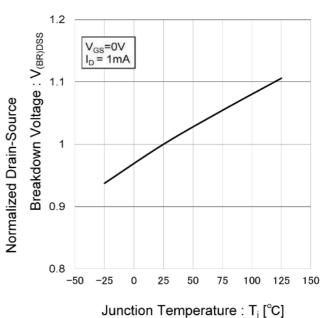


Fig.7 Typical Output Characteristics(I)

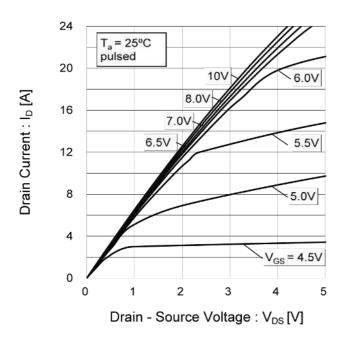
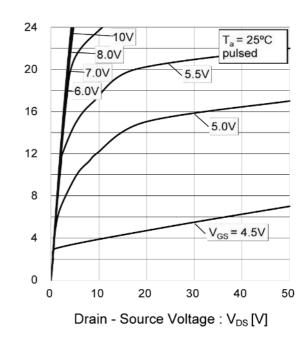


Fig.8 Typical Output Characteristics(II)



Drain Current: Ip [A]

Fig.9 Typical Transfer Characteristics

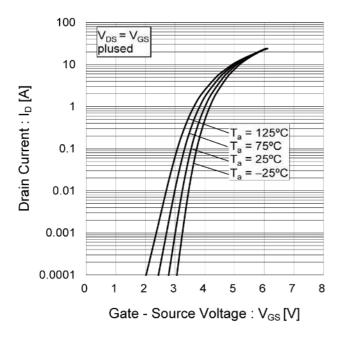


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

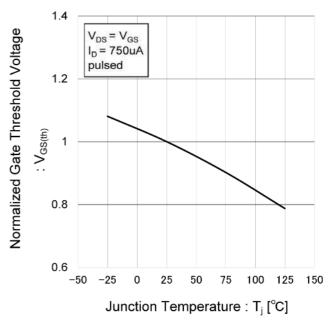


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

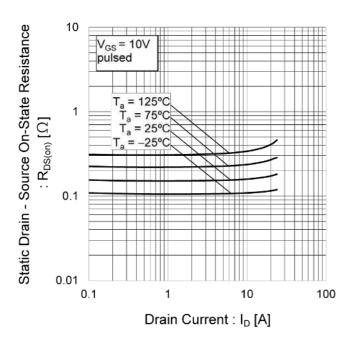


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

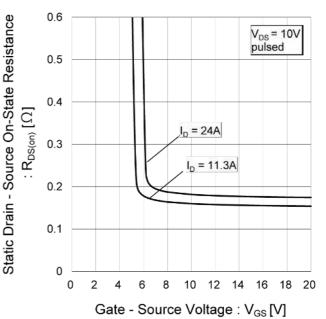


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

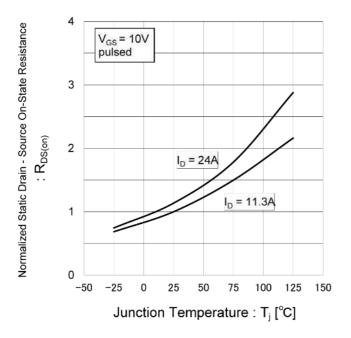


Fig.14 Typical Capacitance vs.

Drain - Source Voltage

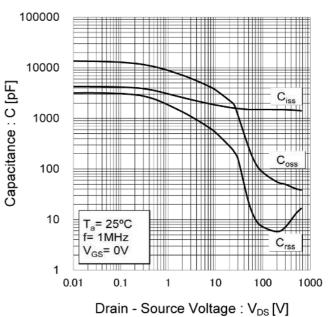


Fig.15 Switching Characteristics

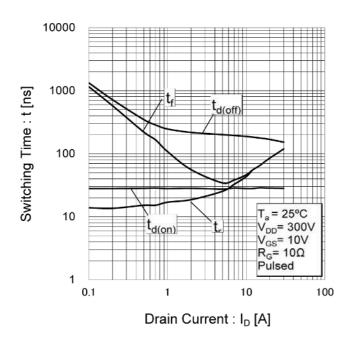
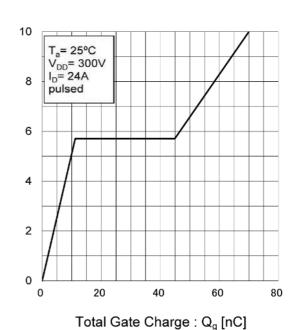


Fig.16 Typical Gate Charge



Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.17 Source Current vs. Source - Drain Voltage

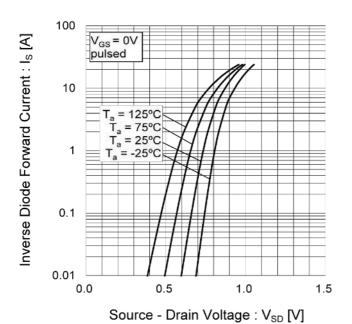
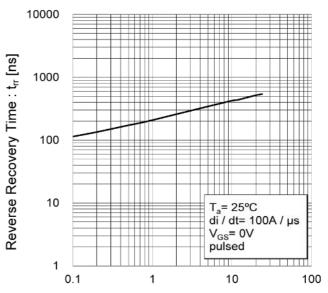


Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current : I<sub>S</sub> [A]

#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

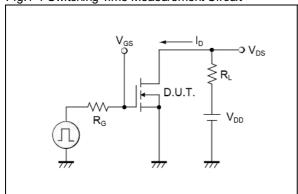


Fig.2-1 Gate Charge Measurement Circuit

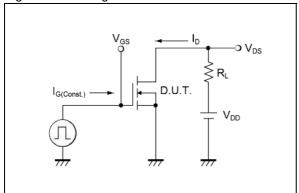


Fig.3-1 Avalanche Measurement Circuit

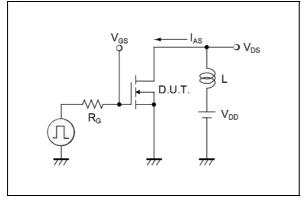


Fig.4-1 trr Measurement Circuit

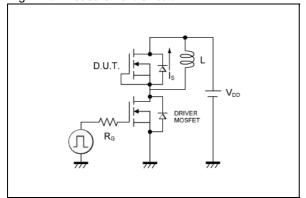


Fig.1-2 Switching Waveforms

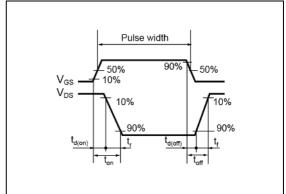


Fig.2-2 Gate Charge Waveform

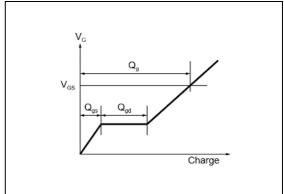


Fig.3-2 Avalanche Waveform

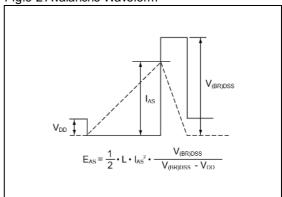
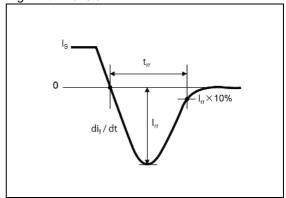
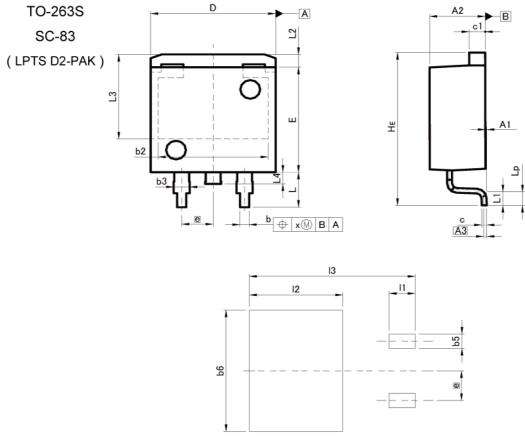


Fig.4-2 trr Waveform



#### Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

D114	MILIM	FTERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.9	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.		0.1	
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1		20	0.0	
L2	1.	10	0.0	43
L3	7.:	25	0.2	85
L4	1.0	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	= 1	0.25	1 A T	0.010
T	MILIM	TERS	INC	HES
DIM H	NATA I	A A A A	A 47 h I	NAAV

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b5	=	1.23	-	0.049
b6	-0	10.40	:=	0.409
11 ]	<u>22</u> 6	2.10		0.083
12	7EX	7.55	11.77	0.297
13	98	13.40	-	0.528

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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